

/ Descriptions

SOD-523

Silicon Diode in a SOD-523 Plastic Package.

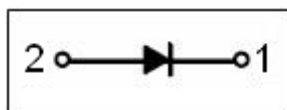
/ Features

Fast switching diodes,HF Product.

/ Applications

Small signal diode.

/ Equivalent Circuit



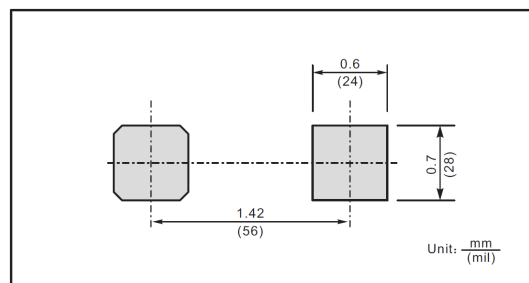
/ Pinning



PIN1:Cathode

PIN2:Anode

The recommended mounting pad size



/ Marking

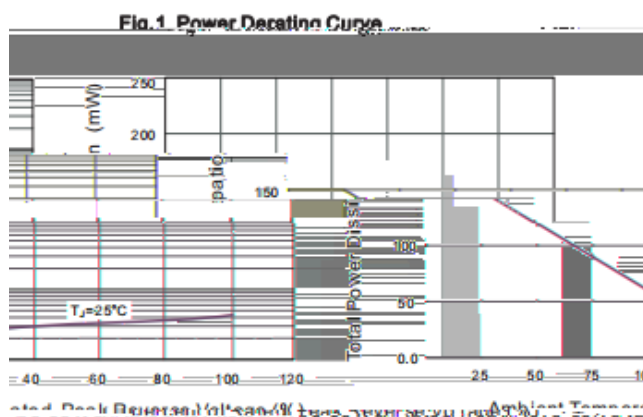
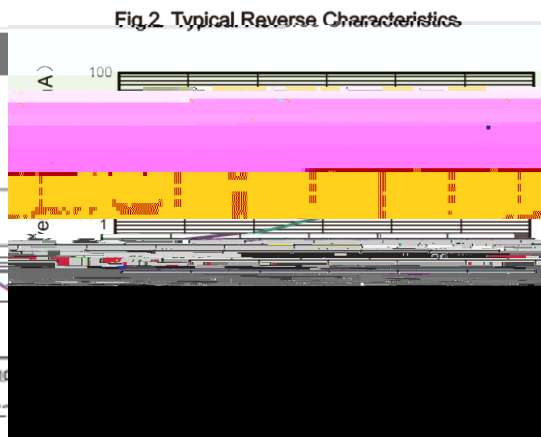
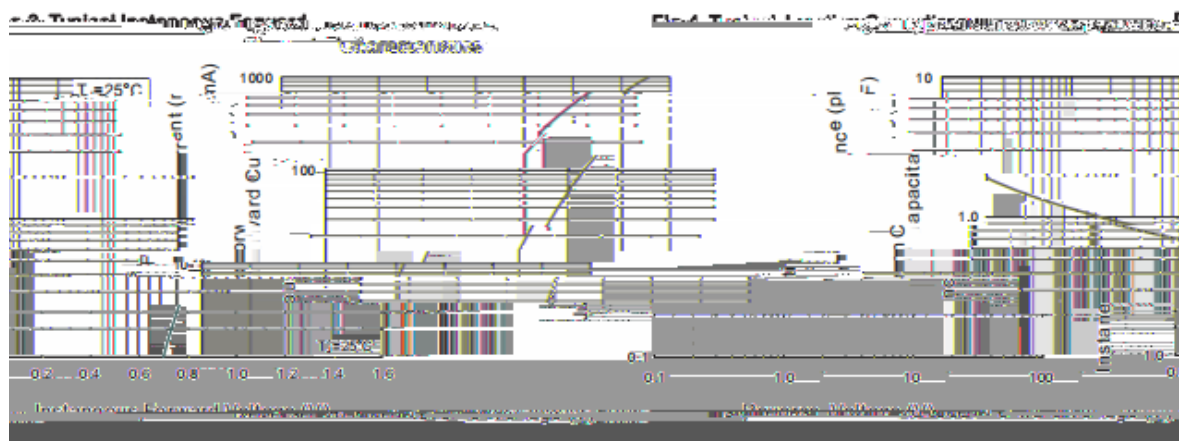
Marking	T4
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	Parameter	Symbol	Rating	Unit
	Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	V
	Maximum RMS voltage	V_{RMS}	75	V
	Continuous Forward Current	I_F	150	mA
	Non-reptitive Peak Forward Surge Current	$I_{FSM} \quad t=1ms$	0.8	A
	Power Dissipation	P_{tot}	150	mW
	Junction Temperature	T_j	-55 150	
	Storage Temperature Range	T_{stg}	-55 150	

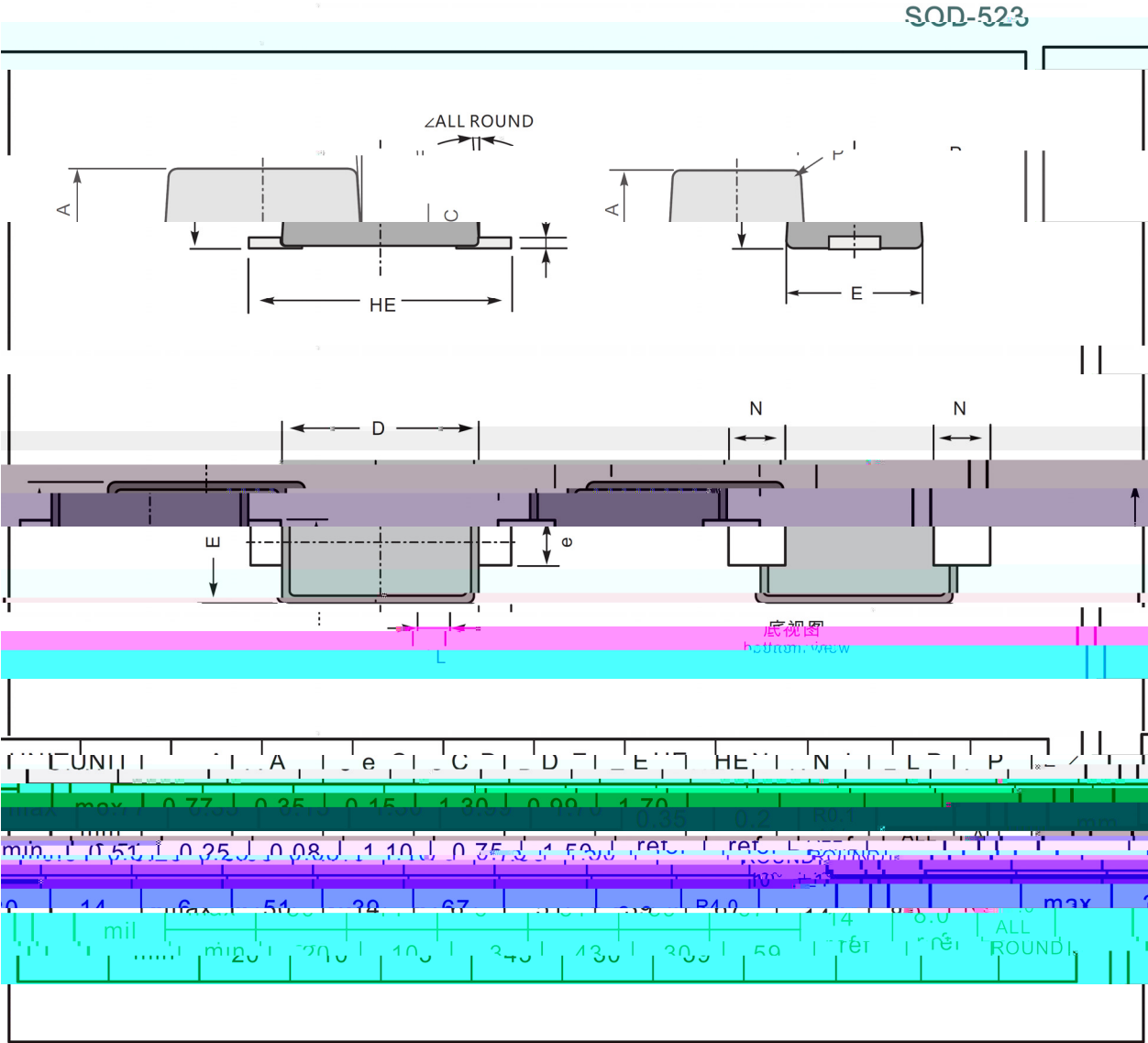
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse Breakdown Voltage	$V_{(BR)R}$	$I_R=1\mu A$	75			V
		$I_F=1mA$			0.715	V
		$I_F=10mA$			0.855	V

V V

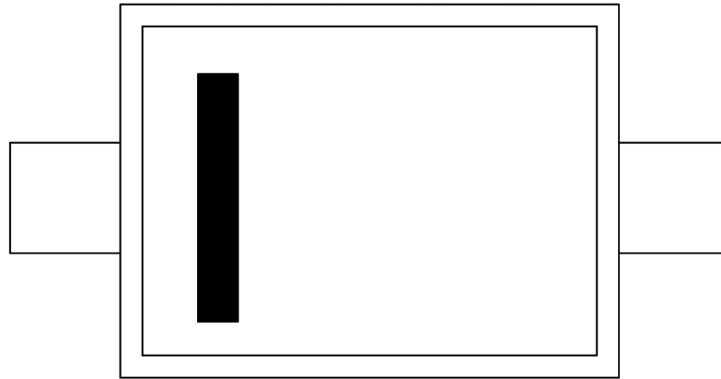
/ Electrical Characteristic Curve



/ Package Dimensions

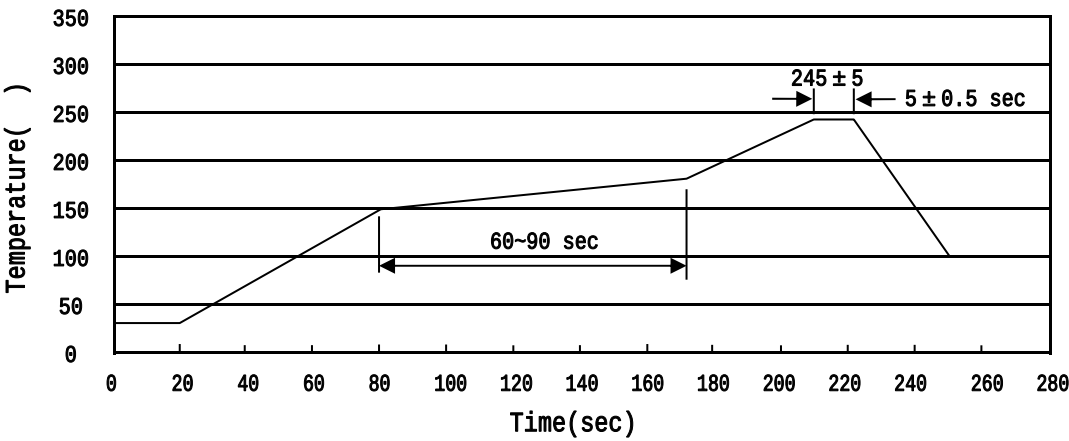


/ Marking Instructions



T4
T563.5ye

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|----|-----------|--|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 °C , Time:60~90sec. |
| 2 | 245±5 | | | 5±0.5sec; | 2.Peak Temp.:245±5 °C , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 °C/sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension (unit mm ³)		
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	Outer Box
SOD-523	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices